5.0 V Micropower 150 mA LDO Linear Regulator with DELAY, Adjustable RESET, and Sense Output

The NCV4279 is a 5.0 V precision micropower voltage regulator with an output current capability of 150 mA.

The output voltage is accurate within $\pm 2.0\%$ with a maximum dropout voltage of 0.5 V at 100 mA. Low quiescent current is a feature drawing only 150 μ A with a 1.0 mA load. This part is ideal for any and all battery operated microprocessor equipment.

Microprocessor control logic includes an active reset output RO with delay and a SI/SO monitor which can be used to provide an early warning signal to the microprocessor of a potential impending reset signal. The use of the SI/SO monitor allows the microprocessor to finish any signal processing before the reset shuts the microprocessor down.

The active Reset circuit operates correctly at an output voltage as low as 1.0 V. The Reset function is activated during the power up sequence or during normal operation if the output voltage drops outside the regulation limits.

The reset threshold voltage can be decreased by the connection of an external resistor divider to the R_{ADJ} lead. The regulator is protected against reverse battery, short circuit, and thermal overload conditions. The device can withstand load dump transients making it suitable for use in automotive environments. The device has also been optimized for EMC conditions.

If the application requires pullup resistors at the logic outputs Reset and Sense Out, the NCV4269 with integrated resistors can be used.

Features

- $5.0 \text{ V} \pm 2.0\% \text{ Output}$
- Low 150 μA Quiescent Current
- Active Reset Output Low Down to $V_0 = 1.0 \text{ V}$
- Adjustable Reset Threshold
- 150 mA Output Current Capability
- Fault Protection
 - ◆ +60 V Peak Transient Voltage
 - → -40 V Reverse Voltage
 - Short Circuit
 - Thermal Overload
- Early Warning through SI/SO Leads
- Internally Fused Leads in SO-14 Package
- Very Low Dropout Voltage
- Electrical Parameters Guaranteed Over Entire Temperature Range
- Pb-Free Packages are Available
- NCV Prefix for Automotive and Other Applications Requiring Site and Control Changes



ON Semiconductor®

http://onsemi.com

MARKING DIAGRAMS

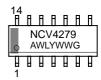


SO-8 D SUFFIX CASE 751





SO-14 D SUFFIX CASE 751A



A = Assembly Location

WL, L = Wafer Lot YY, Y = Year WW. W = Work Week

•. G = Lead Free Indicators

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 12 of this data sheet.

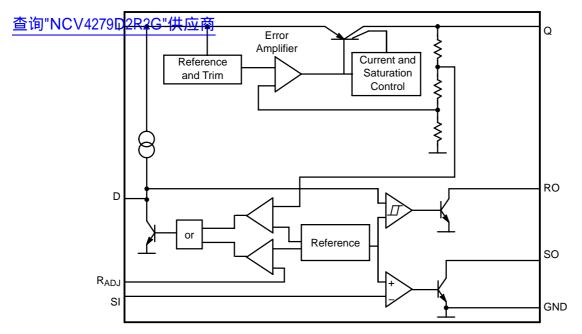


Figure 1. Block Diagram

PIN CONNECTIONS



PACKAGE PIN DESCRIPTION

Package Pin Number						
SO-8	SO-14	Pin Symbol	Function			
3	1	R _{ADJ}	Reset Threshold Adjust; if not used to connect to GND.			
4	2	D	Reset Delay; To Set Time Delay, Connect to GND with a Capacitor			
5	3, 4, 5, 6, 10, 11, 12	GND	Ground			
6	7	RO	Reset Output; This is an Open-Collector Output. Leave Open if Not Used.			
7	8	SO	Sense Output; This is an Open-Collector Output. If not used, keep open.			
8	9	Q	5 V Output; Connect to GND with a 10 μF Capacitor, ESR < 10 Ω .			
1	13	I	Input; Connect to GND Directly at the IC with a Ceramic Capacitor.			
2	14	SI	Sense Input; If not used, Connect to Q.			

NCV4279

MAXIMUM RAZINGS2R2号4供可应商0°C)

Parameter		Symbol	Min	Max	Unit
Input to Regulator			-40 Internally Limited	45 Internally Limited	V
Input Peak Transient Voltage	VI	-	60	٧	
Sense Input		V _{SI} I _{SI}	-40 -1	45 1	V mA
Reset Threshold Adjust		V _{RADJ} I _{RADJ}	-0.3 -10	7 10	V mA
Reset Delay		V _D	-0.3 Internally Limited	7 Internally Limited	V
Ground		Iq	50	-	mA
Reset Output		V _{RO}	-0.3 Internally Limited	7 Internally Limited	V
Sense Output		V _{SO}	-0.3 Internally Limited	7 Internally Limited	V
Regulated Output		V _Q I _Q	-0.5 -10	7.0 -	V mA
Junction Temperature Storage Temperature		T _J T _{STG}	- -50	150 150	°C °C
Input Voltage Operating Range Junction Temperature Operating Range		V _I T _J	- -40	45 150	°C
Junction-to-Ambient Thermal Resistance	SO-8 SO-14	$R_{ heta JA}$	-	200 70	k/W
Junction-to-Pin 4, all GND Pins Grounded.	SO-14	$R_{\theta JP}$	-	30	k/W

Lead Temperature Soldering and MSL

Parameter	Symbol	Value	Unit
MSL, 8-Lead, 14-Lead, LS Temperature 260°C Peak (Notes 3, 4)	MSL	1	_

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

- 1. This device series incorporates ESD protection and exceeds the following ratings: Human Body Model (HBM) ≤ 2.0 kV per JEDEC standard: JESD22–A114. Machine Model (MM) ≤ 200 V per JEDEC standard: JESD22-A115
- Latchup Current Maximum Rating: ≤ 150 mA per JEDEC standard: JESD78.
 Lead free: 60–150 Sec above 217°C, 40 Sec Max at Peak, 265°C Peak.
- 4. Leaded; 60–150 Sec above 183°C, 30 Sec Max at Peak, 240°C Peak.

NCV4279

ELECTRICAL CHARACTERISTICS: $T_J = -40^{\circ}C \le T_J \le 125^{\circ}C$, $V_I = 13.5$ V unless otherwise specified)

Characteristic	Symbol	Test Conditions	Min	Тур	Max	Unit	
REGULATOR							
Output Voltage	V_{Q}	1 mA \leq I _Q \leq 100 mA; 6 V \leq V _I \leq 16 V	4.90	5.00	5.10	V	
Current Limit	IQ	-	150	200	500	mA	
Current Consumption; $I_q = I_I - I_Q$	Iq	I _Q = 1 mA, RO, SO High	-	150	250	μΑ	
Current Consumption; $I_q = I_I - I_Q$	Iq	I _Q = 10 mA, RO, SO High	ı	250	450	μΑ	
Current Consumption; $I_q = I_I - I_Q$	Iq	I _Q = 50 mA, RO, SO High	ı	2.0	3.0	mA	
Dropout Voltage	V _{dr}	I _Q = 100 mA (Note 5)	ı	0.25	0.5	V	
Load Regulation	Δ_{VQ}	I _Q = 5 mA to 100 mA	-	10	20	mV	
Line Regulation	Δ_{VQ}	V _I = 6 V to 26 V; I _Q = 1 mA	1	10	30	mV	
RESET GENERATOR							
Reset Switching Threshold	V _{RT}	-	4.50	4.65	4.80	V	
Reset Adjust Switching Threshold	$V_{RAD,JTH}$	V _Q > 3.5 V	1.26	1.35	1.44	V	
Reset Output Saturation Voltage	V _{RO,SAT}	$V_Q < V_{RT}$, $R_{RO} = 20 \text{ k}\Omega$	ı	0.1	0.4	V	
Upper Delay Switching Threshold	V _{UD}	-	1.4	1.8	2.2	V	
Lower Delay Switching Threshold	V_{LD}	-	0.3	0.45	0.60	V	
Saturation Voltage on Delay Capacitor	V _{D,SAT}	V _Q < V _{RT}	-	-	0.1	V	
Charge Current	I _D	V _D = 1 V	3.0	6.5	9.5	μΑ	
Delay Time L → H	t _d	C _D = 100 nF	17	28	_	ms	
Delay Time H → L	t _t	C _D = 100 nF	1	1.0	_	μS	
INPUT VOLTAGE SENSE	•			-	=	-	
Sense Threshold High	V _{SI} , High	-	1.24	1.31	1.38	V	
Sense Threshold Low	V _{SI} , Low	-	1.16	1.20	1.28	V	
Sense Output Saturation Voltage	V _{SO} , Low	V_{SI} < 1.20 V; V_{Q} > 3 V; R_{SO} = 20 k Ω	ı	0.1	0.4	V	
Sense Input Current	I _{SI}	-	-1.0	0.1	1.0	μΑ	

^{5.} Dropout voltage = V_I – V_Q measured when the output voltage has dropped 100 mV from the nominal value obtained at 13.5 V input.

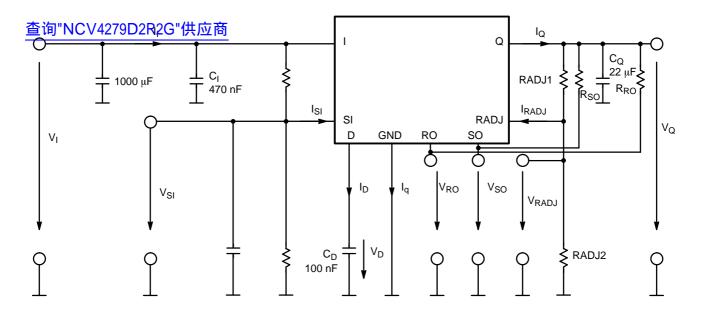


Figure 2. Measuring Circuit

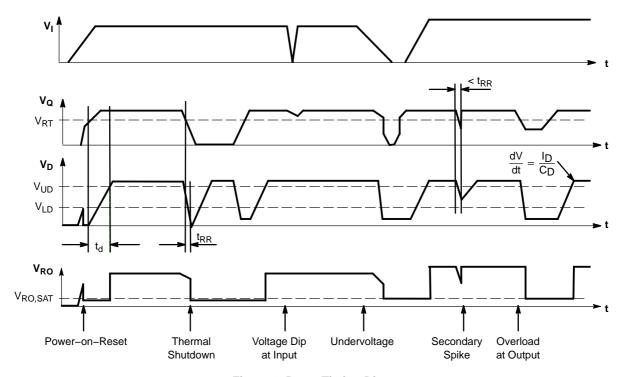


Figure 3. Reset Timing Diagram

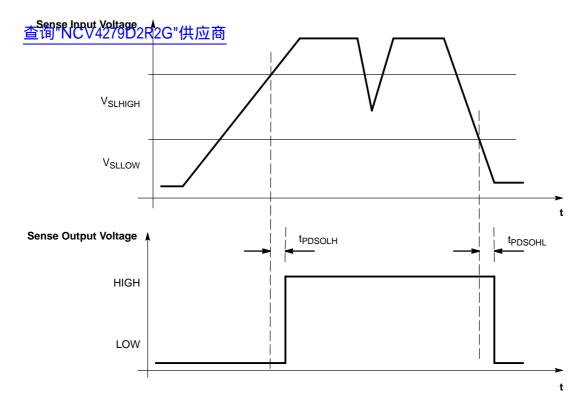
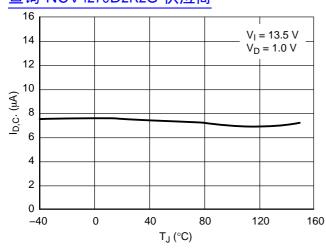


Figure 4. Sense Timing Diagram

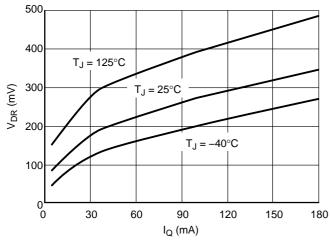
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3.2 $V_1 = 13.5 \text{ V}$ 2.8 2.4 2.0 V_{UD} $V_D, (V)$ 1.6 1.2 0.8 V_{LD} 0.4 0 0 -40 40 80 120 160 T_J (°C)

Figure 5. Charge Current I_D,c vs. Temperature T_J

Figure 6. Switching Voltage V_{UD} and V_{LD} vs. Temperature T_J



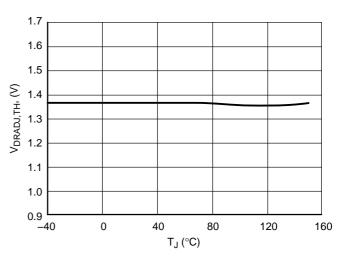
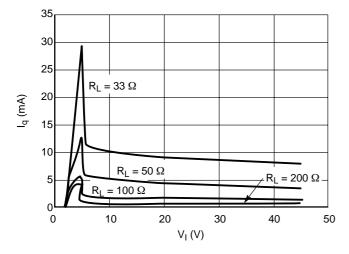


Figure 7. Drop Voltage V_{DR} vs. Output Current I_{Q}

Figure 8. Reset Adjust Switching Threshold $V_{RADJ,TH}$ vs. Temperature T_J



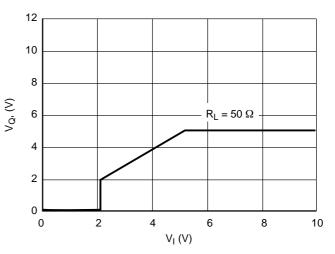
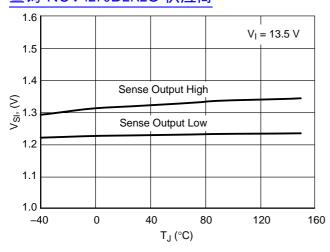


Figure 9. Current Consumption I_q vs. Input Voltage V_l

Figure 10. Output Voltage V_Q vs. Input Voltage V_I

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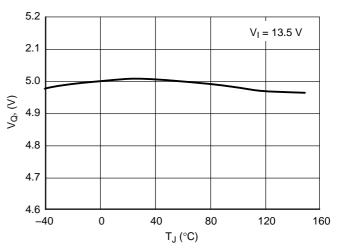


Figure 11. Sense Threshold V_{SI} vs. Temperature T_J

Figure 12. Output Voltage V_Q vs. Temperature T_J

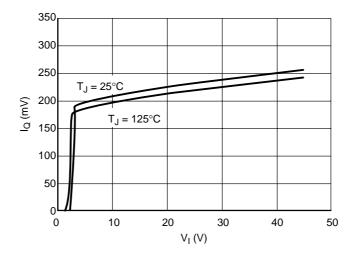
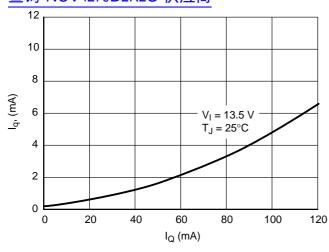


Figure 13. Output Current I_Q vs. Input Voltage V_I

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1.6 1.4 1.2 1.0 I_q, (mA) $V_{I} = 13.5 \text{ V}$ $T_J = 25^{\circ}C$ 8.0 0.6 0.4 0.2 0, 10 30 50 I_Q (mA)

Figure 14. Current Consumption $\mathbf{I_q}$ vs. Output Current $\mathbf{I_Q}$

Figure 15. Current Consumption I_q vs. Output Current I_Q

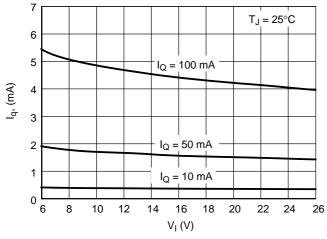


Figure 16. Current Consumption $\mathbf{I_q}$ vs. Input Voltage $\mathbf{V_l}$

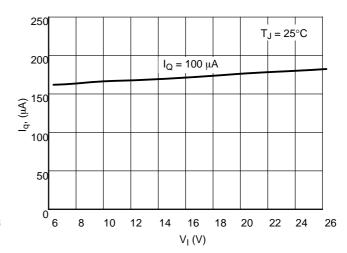


Figure 17. Current Consumption I_q vs. Input Voltage V_I

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APPLICATION DESCRIPTION

OUTPUT REGULATOR

The output is controlled by a precision trimmed reference. The PNP output has drive quiescent current control for regulation while the input voltage is low, preventing over saturation. Current limit and voltage monitors complement the regulator design to give safe operating signals to the processor and control circuits.

RESET OUTPUT (RO)

A reset signal, Reset Output, RO, (low voltage) is generated as the IC powers up. After the output voltage V_Q increases above the reset threshold voltage V_{RT} , the delay timer D is started. When the voltage on the delay timer V_D passes V_{UD} , the reset signal RO goes high. A discharge of the delay timer V_D is started when V_Q drops and stays below the reset threshold voltage V_{RT} . When the voltage of the delay timer V_D drops below the lower threshold voltage V_{LD} the reset output voltage V_{RO} is brought low to reset the processor.

The reset output RO is an open collector NPN transistor, controlled by a low voltage detection circuit. The circuit is functionally independent of the rest of the IC, thereby guaranteeing that RO is valid for $V_{\rm O}$ as low as 1.0 V.

RESET ADJUST (RADJ)

The reset threshold V_{RT} can be decreased from a typical value of 4.65 V to as low as 3.5 V by using an external voltage divider connected from the Q lead to the pin RADJ, as shown in Figure 18. The resistor divider keeps the voltage above the $V_{RADJ,TH}$ (typical 1.35 V) for the desired input voltages, and overrides the internal threshold detector. Adjust the voltage divider according to the following relationship:

$$V_{RT} = V_{RADJ,TH} \cdot (R_{ADJ1} + R_{ADJ2}) / R_{ADJ2}$$
 (eq. 1)

If the reset adjust option is not needed, the R_{ADJ} pin should be connected to GND causing the reset threshold to go to its default value (typically 4.65 V).

RESET DELAY (D)

The reset delay circuit provides a delay (programmable by capacitor C_D) on the reset output lead RO. The delay lead D provides charge current I_D (typically 6.5 μ A) to the external delay capacitor C_D during the following times:

- During Powerup (once the regulation threshold has been exceeded).
- 2. After a reset event has occurred and the device is back in regulation. The delay capacitor is set to discharge when the regulation (V_{RT} , reset threshold voltage) has been violated. When the delay capacitor discharges to V_{LD} , the reset signal RO pulls low.

SETTING THE DELAY TIME

The delay time is set by the delay capacitor C_D and the charge current I_D . The time is measured by the delay capacitor voltage charging from the low level of V_{DSAT} to the higher level V_{UD} . The time delay follows the equation:

$$t_d = [C_D (V_{UD} - V_{DSAT})]/I_D$$
 (eq. 2)

Example:

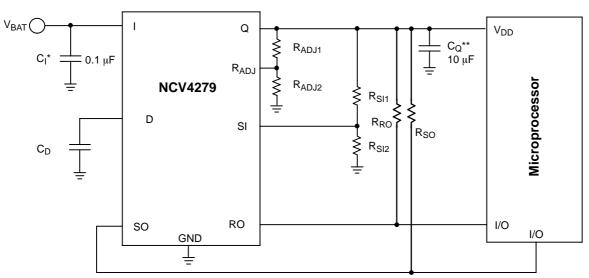
Using $C_D = 100 \text{ nF}$.

Use the typical value for $V_{DSAT} = 0.1 \text{ V}$.

Use the typical value for $V_{\rm UD} = 1.8 \text{ V}$.

Use the typical value for Delay Charge Current $I_D = 6.5 \mu A$.

$$t_d = [100 \text{ nF} (1.8 - 0.1 \text{ V})]/6.5 \,\mu\text{A} = 26.2 \,\text{ms}$$
 (eq. 3)



^{*}C_I required if regulator is located far from the power supply filter.

Figure 18. Application Diagram

^{**} C_Q required for Stability. Cap must operate at minimum temperature expected.

SENSE INPUT (SI) / SENSE OUTPUT (SO) VOLTAGE MONTOR V4279D2R2G 供应商

An on-chip comparator is available to provide early warning to the microprocessor of a possible reset signal. The output is from an open collector driver. The reset signal typically turns the microprocessor off instantaneously. This can cause unpredictable results with the microprocessor. The signal received from the SO pin will allow the microprocessor time to complete its present task before shutting down. This function is performed by a comparator referenced to the band gap voltage. The actual trip point can be programmed externally using a resistor divider to the input monitor SI (Figure 18). The values for R_{SI1} and R_{SI2} are selected for a typical threshold of 1.20 V on the SI Pin.

SIGNAL OUTPUT

Figure 19 shows the SO Monitor timing waveforms as a result of the circuit depicted in Figure 18. As the output voltage (V_Q) falls, the monitor threshold (V_{SILOW}), is crossed. This causes the voltage on the SO output to go low sending a warning signal to the microprocessor that a reset signal may occur in a short period of time. $T_{WARNING}$ is the time the microprocessor has to complete the function it is currently working on and get ready for the reset shutdown signal.

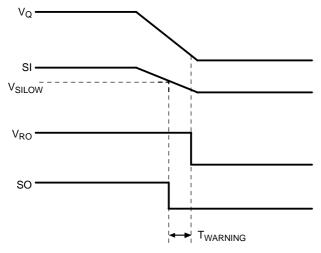


Figure 19. SO Warning Waveform Time Diagram

STABILITY CONSIDERATIONS

The input capacitor C_I in Figure 18 is necessary for compensating input line reactance. Possible oscillations caused by input inductance and input capacitance can be damped by using a resistor of approximately 1.0 Ω in series with C_I .

The output or compensation capacitor helps determine three main characteristics of a linear regulator: startup delay, load transient response and loop stability.

The capacitor value and type should be based on cost, availability, size and temperature constraints. A tantalum or aluminum electrolytic capacitor is best, since a film or ceramic capacitor with almost zero ESR can cause instability. The aluminum electrolytic capacitor is the least

expensive solution, but, if the circuit operates at low temperatures (-25°C to -40°C), both the value and ESR of the capacitor will vary considerably. The capacitor manufacturer's data sheet usually provides this information.

The value for the output capacitor C_Q shown in Figure 18 should work for most applications; however, it is not necessarily the optimized solution. Stability is guaranteed at values $C_Q = 10~\mu F$ and an ESR = $10~\Omega$ within the operating temperature range. Actual limits are shown in a graph in the typical data section.

CALCULATING POWER DISSIPATION IN A SINGLE OUTPUT LINEAR REGULATOR

The maximum power dissipation for a single output regulator (Figure 18) is:

$$P_{D(max)} = [V_{I(max)} - V_{Q(min)}]I_{Q(max)} + V_{I(max)}I_{q} \text{ (eq. 4)}$$

where

 $V_{I(max)}$ is the maximum input voltage,

 $V_{Q(min)}$ is the minimum output voltage,

 $I_{Q(max)}$ is the maximum output current for the application, and I_q is the quiescent current the regulator consumes at $I_{Q(max)}$.

Once the value of $P_{D(max)}$ is known, the maximum permissible value of $R_{\theta JA}$ can be calculated:

$$R_{\theta JA} = (150^{\circ}C - T_A) / P_D$$
 (eq. 5)

The value of $R_{\theta JA}$ can then be compared with those in the package section of the data sheet. Those packages with $R_{\theta JA}$'s less than the calculated value in equation 2 will keep the die temperature below 150°C. In some cases, none of the packages will be sufficient to dissipate the heat generated by the IC, and an external heatsink will be required. The current flow and voltages are shown in the Measurement Circuit Diagram.

HEATSINKS

A heatsink effectively increases the surface area of the package to improve the flow of heat away from the IC and into the surrounding air.

Each material in the heat flow path between the IC and the outside environment will have a thermal resistance. Like series electrical resistances, these resistances are summed to determine the value of $R_{\theta JA}$:

$$R_{\theta}JA = R_{\theta}JC + R_{\theta}CS + R_{\theta}SA$$
 (eq. 6)

where:

 $R_{\theta JC}$ = the junction-to-case thermal resistance,

 $R_{\theta CS}$ = the case–to–heat sink thermal resistance, and

 $R_{\theta SA}$ = the heat sink-to-ambient thermal resistance.

 $R_{\theta JC}$ appears in the package section of the data sheet. Like $R_{\theta JA}$, it too is a function of package type, $R_{\theta CS}$ and $R_{\theta SA}$ are functions of the package type, heatsink and the interface between them. These values appear in data sheets of heatsink manufacturers. Thermal, mounting, and heatsinking considerations are discussed in the ON Semiconductor application note AN1040/D, available on the ON Semiconductor website.

NCV4279

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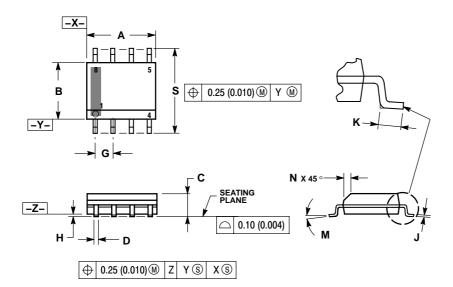
Device	Output Voltage	Package	Shipping [†]
NCV4279D1		SO-8	
NCV4279D1G		SO-8 (Pb-Free)	98 Units/Rail
NCV4279D1R2		SO-8	
NCV4279D1R2G		SO-8 (Pb-Free)	2500 Tape & Reel
NCV4279D2	5.0 V	SO-14	
NCV4279D2G	7	SO-14 (Pb-Free)	55 Units/Rail
NCV4279D2R2		SO-14	
NCV4279D2R2G		SO-14 (Pb-Free)	2500 Tape & Reel

[†]For information on tape and reel specifications,including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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PACKAGE DIMENSIONS

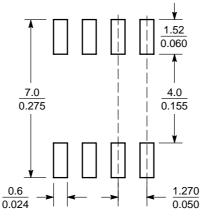
SO-8 D SUFFIX CASE 751-07 **ISSUE AF**



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER
- ANSI Y14.5M, 1982.
 CONTROLLING DIMENSION: MILLIMETER.
 DIMENSION A AND B DO NOT INCLUDE
 MOLD PROTRUSION.
- MOLD PROTRUSION.
 MAXIMUM MOLD PROTRUSION 0.15 (0.006)
 PER SIDE.
 DIMENSION D DOES NOT INCLUDE DAMBAR
 PROTRUSION. ALLOWABLE DAMBAR
 PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION. 751–01 HRU 751–06 ARE OBSOLETE. NEW STANDARD IS 751–07.

	MILLIN	IETERS	INCHES	
DIM	MIN MAX		MIN	MAX
Α	4.80	5.00	0.189	0.197
В	3.80	4.00	0.150	0.157
C	1.35	1.75	0.053	0.069
ם	0.33	0.51	0.013	0.020
G	1.27 BSC		0.050 BSC	
H	0.10	0.25	0.004	0.010
7	0.19	0.25	0.007	0.010
K	0.40	1.27	0.016	0.050
М	0 °	0 ° 8 °		8 °
N	0.25	0.50	0.010	0.020
s	5.80	6.20	0.228	0.244

SOLDERING FOOTPRINT*



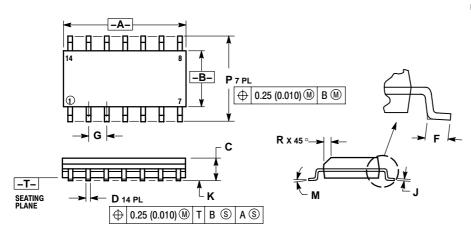
 $\left(\frac{\text{mm}}{\text{inches}}\right)$ SCALE 6:1

^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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PACKAGE DIMENSIONS

SO-14 D SUFFIX CASE 751A-03 ISSUE G



NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: MILLIMETER.
 DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
- 4. MAXIMUM MOLD PROTRUSION 0.15 (0.006)
 PER SIDE
- 5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIN	IETERS	INCHES	
DIM	MIN	MAX	MIN	MAX
Α	8.55	8.75	0.337	0.344
В	3.80	4.00	0.150	0.157
С	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.80	6.20	0.228	0.244
R	0.25	0.50	0.010	0.019

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